

ABSTRACT

A high-density electronics package compromises a chip-stack having a plurality of ICs. Oblong-shaped bumps comprising an electrically-conductive bonding material are disposed along one side of each IC in the chip-stack. The one side of each IC bearing the bumps is aligned with the bump-bearing side of all other ICs in the chip-stack. A portion of each oblong-shaped bump extends beyond the edge of its host IC. This portion of each bump is available to electrically and mechanically connect the chip stack to the next packaging layer, such as a printed circuit board.